ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	Bannockburr	n, Illinois. A	ll rights reserved utions.	under both Ie	his docume vel parts, t	ent is a declar he declaratio	ation of the	e substance sses all low	s within the manufact er level materials for	urer listed which the	item. Note manufactur	e: if the item is an a rer has engineering	ssembly with lower responsibility.	
					Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/No, Homogeneous Mate				rials and N	tials and Mfg Information				
Supplier Information														
Company name*	Company unique ID			1	Unique ID Authority					Response Date*				
onsemi								2024-05-17						
Contact Name Title - Contact			t	Ph			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product En			luct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			entative	Pho			hone - Representative*			Email -	Email - Representative*			
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	er Mfr Item Nur		Number Mfr Item Name			Effective Da	te Versio	on	Manufacturing Site		Weight*	UOM	Unit Type	
	NCP810744	CP81074AMNTBG Single Channel MOSFET Drive		0A High Speed Lo (8LD DFN-A)	w-Side	e 2024-05-17			PH1		9.41	mg	Each	
Manufacturing Proccess Information	n													
Terminal Plating / Grid Array Mater	Terminal Plating / Grid Array Material Terminal Base Alloy		Alloy	J-STD-020 MSL R	Rating	Peak Pr	ocess Body	/ Temperatu	are Max Time at Pea	ık Tempera	ature Nur	mber of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	seco	nds 3				
Comments														
level 1 - maximum time at peak temperature	during solde	ring is 10-3	0 seconds											
For more information regarding material con	nposition ple	ease refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.1	mg	Supplier	Silicon (Si)	7440-21-3		0.1	mg
Die Attach	0.24	mg	Supplier	Silver (Ag)	7440-22-4		0.18	mg
			Supplier	Epoxy resins	129915-35-1		0.06	mg
Lead Frame	3.71	mg	Supplier	Zinc (Zn)	7440-66-6		0.0037	mg
			Supplier	Iron (Fe)	7439-89-6		0.0853	mg
			Supplier	Copper (Cu)	7440-50-8		3.6173	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	5.0	mg		Epoxy resin	proprietary data		0.235	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.5	mg
			Supplier	Carbon Black (C)	1333-86-4		0.005	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.025	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.235	mg
Plating	0.29	mg	Supplier	Palladium (Pd)	7440-05-3		0.007	mg
			В	Nickel (Ni)	7440-02-0		0.2552	mg
			Supplier	Gold (Au)	7440-57-5		0.0278	mg
Wire Bond	0.07	mg	Supplier	Palladium (Pd)	7440-05-3		0.0007	mg
			Supplier	Copper (Cu)	7440-50-8		0.0693	mg